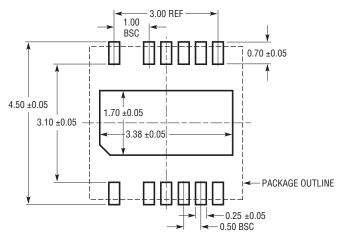
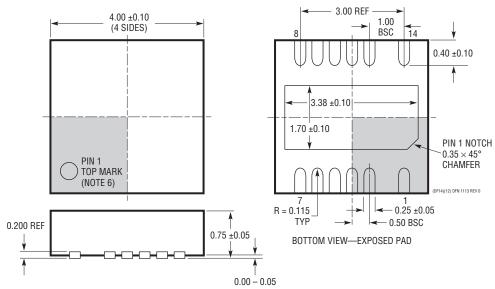
$\begin{array}{c} \text{DF Package} \\ \text{14(12)-Lead Plastic DFN (4mm} \times \text{4mm)} \end{array}$

(Reference LTC DWG # 05-08-1963 Rev Ø)



RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



- 1. PACKAGE OUTLINE DOES NOT CONFORM TO JEDEC MO-229
- 2. DRAWING NOT TO SCALE
- 2. DIMWING UNTO SOSTED ARE IN MILLIMETERS
 4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.15mm ON ANY SIDE
- 5. EXPOSED PAD SHALL BE SOLDER PLATED
- 6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE